

AMENDMENTS TO THE SPECIFICATION:

Please amend the paragraph beginning on page 2, line 10 as follows:

As shown in Figs. 10 and 11, in ~~in~~ the structure of the conventional ceramic package, when a distance λ (~~Figs. 10 and 11~~) from a connection interface c-c' between the coplanar line 4a and inner layer line 4b to the center of the endmost via hole 8b formed to extend through the first and second layer substrates 1a and 1b increases with respect to a signal wavelength, a signal is radiated in an outward propagation mode between the connection interface c-c' and the endmost via hole 8b into a plane-parallel plate, constituted by the ground conductor 6b of the coplanar line 4a and the ground conductor 6c on the upper surface of the second layer substrate 1b. Studies made by the present inventors clarified that in the conventional ceramic package, the transmission characteristics in the feed-through 4 degraded due to this signal radiation.

Please amend the paragraph beginning on page 5, line 26 as follows:

As shown in Figs. 1, 2 and 3, the feed-through 104 is comprised of a coplanar line 104a formed on the first layer substrate 101a, and an inner layer line 104b obtained by forming the second layer substrate 101b on the coplanar line 104a. More specifically, the inner layer line 104b is comprised of the coplanar line 104a formed between the first and second layer substrates 101a and 101b. The feed-through 104 has a conductor structure consisting of a signal conductor (strip conductor) 105 formed on the upper surface of the first layer substrate 101a, a ground conductor 106a formed on the lower surface of the first layer substrate 101a, a pair of ground conductors (planar ground conductors) 106b formed on two sides of the signal conductor 105 at a predetermined gap, and a ground conductor 106c formed on the upper surface of the second layer substrate 101b. The cavity 103 is hermetically sealed by an upper lid 107 so that it is hermetically held.

Please amend the paragraph beginning on page 6, line 17 as follows:

As shown in Fig. 4, in order to equalize electric potential, via holes 108a for connecting the ground conductors 106a and 106b to each other are formed to extend through the first layer substrate 101a, and via holes 108b for connecting the ground conductors 106a, 106b, and 106c to each other are formed to extend through the first and second layer substrates 101a and 101b. The via holes 108a and 108b are formed in two rows along the signal conductor. In this case, pitches λ_{p1} and λ_{p2} of the respective via holes 108a and 108b in the signal propagating direction desirably satisfy the following expressions (1) and (2):

$$\lambda_{p1} < \frac{c}{2f\sqrt{\frac{\epsilon_r + 1}{2}}} \quad \dots (1)$$

$$\lambda_{p2} < \frac{c}{2f\sqrt{\epsilon_r}} \quad \dots (2)$$

where c , f , and ϵ_r respectively indicate the speed of light, the signal frequency, and the specific dielectric constant of the dielectric substrate.